

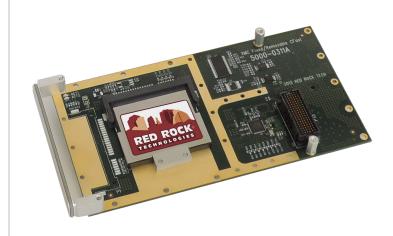
RRT-XMC-CFast-F-A XMC CFast Module: Air Cooled

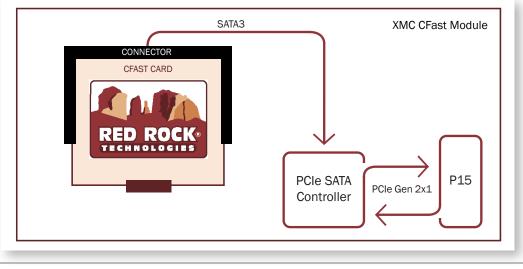
THE XMC CFAST MODULE: AIR COOLED is a mezzanine storage module with a PCI Express SATA 3 controller that supports one fixed CFast.

Provides boot drive and/or disk storage for VPX, VME, cPCI and ATCA single board computers (SBCs) with XMC Slot.

CFast is same form factor as Compact Flash but with SATA interface thus providing faster throughput.

- XMC PCIe Gen 2x1 interface per VITA 42.3
- Transfer rates up to 500 MB/s
- CFast capacities up to 1TB
- CFast connectors rated for 10,000 mating cycles
- Air cooled
- Wide range of COTS CFast options
- CFast secured by rugged retainer clip
- High performance SATA3 transfer rates. Backwards compatible with SATA1/2
- Compatible with all SBCs with XMC slot
- Meets XMC VITA 42 height requirements
- –X version rated for -40°C to 85°C
- CFast with write protect switch available
- Front panel activity LED
- ROHS compliant



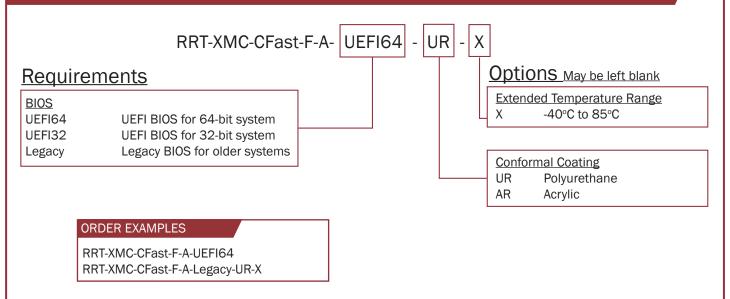


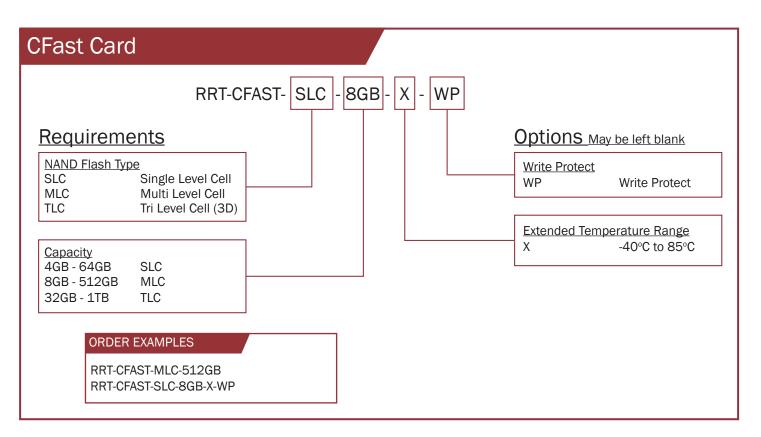
(480)-483-3777

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Ordering Information

XMC CFast Module: Air Cooled





(480)-483-3777 •

Product Specifications

XMC CFAST MODULE: AIR COOLED

PERFORMANCE	
CAPACITIES	Up to 1TB
XMC INTERFACE	VITA 42.3/PCIe 2.0x1 Compliant
XMC INTERFACE SPEED (PCIe GEN1/GEN2)	2.5/5Gbits/s
CFAST INTERFACE	SATA 3 backwards compatible with SATA 1/2
SECTOR SIZE	512 bytes
RELIABILITY	
MTBF - XMC MODULE ¹	3 million hours
POWER	
VOLTAGE	VPWR +5V +/- 5% or +12V +/- 5%, +3.3+/- 0.3V
WATTS (IDLE)	1.2 W
WATTS (ACTIVE)	2.5 W
ENVIRONMENTAL	
OPERATING TEMPERATURE	0°C to 70°C
EXTENDED OPERATING TEMPERATURE ²	-40°C to 85°C
STORAGE TEMPERATURE	-55°C to 95°C
ALTITUDE	80,000 ft. (24,000 meters)
RELATIVE HUMIDITY	5% to 95% non-condensing
SHOCK	20g, 11 millisecond terminal sawtooth pulse
VIBRATION	0.04g ² /Hz, 100 Hz to 1000 Hz
PHYSICAL	
FORM FACTOR	XMC
WEIGHT	3.5 oz. (100g max)
NOTES	
(1) Telcordia SR-322, Issue 3, operating temp (40C), electrical stress (50%), environmental factor (1.0). (2) Thermal gualification per MIL-STD-810, Method 501 Procedure II, and MIL-STD-810, Method 502, Procedure II,	

(2) Thermal qualification per MIL-STD-810, Method 501 Procedure II, and MIL-STD-810, Method 502, Procedure II.



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